

## **FMP05N50E**

**FUJI POWER MOSFET** 

### Super FAP-E<sup>3</sup> series

#### **N-CHANNEL SILICON POWER MOSFET**

#### ■ Features

Maintains both low power loss and low noise Lower  $R_{DS}(on)$  characteristic More controllable switching dv/dt by gate resistance Smaller  $V_{GS}$  ringing waveform during switching Narrow band of the gate threshold voltage (3.0±0.5V) High avalanche durability

#### Applications

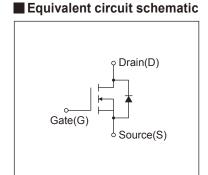
Switching regulators UPS (Uninterruptible Power Supply) DC-DC converters

#### ■ Maximum Ratings and Characteristics

#### ● Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)

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■ Outline Drawings [mm]



Description	Symbol	Characteristics	Unit	Remarks
Proin Source Voltage	V <sub>DS</sub>	500	V	
Drain-Source Voltage	V <sub>DSX</sub>	500	V	V <sub>GS</sub> = -30V
Continuous Drain Current	ID	±5	Α	
Pulsed Drain Current	IDP	±20	Α	
Gate-Source Voltage	V <sub>GS</sub>	±30	V	
Repetitive and Non-Repetitive Maximum Avalanche Current	IAR	5	Α	Note*1
Non-Repetitive Maximum Avalanche Energy	Eas	171	mJ	Note*2
Repetitive Maximum Avalanche Energy	Ear	6.0	mJ	Note*3
Peak Diode Recovery dV/dt	dV/dt	5.3	kV/μs	Note*4
Peak Diode Recovery -di/dt	-di/dt	100	A/µs	Note*5
Maximum Power Dissipation	Po	2.02	W	Ta=25°C
		60	VV	Tc=25°C
Operating and Storage Temperature range	Tch	150	°C	
	Tstg	-55 to +150	°C	

#### ● Electrical Characteristics at Tc=25°C (unless otherwise specified)

Description	Symbol	Conditions	Conditions		typ.	max.	Unit
Drain-Source Breakdown Voltage	BVoss	I <sub>D</sub> =250µA, V <sub>GS</sub> =0V		500	-	-	V
Gate Threshold Voltage	V <sub>GS</sub> (th)	In=250µA, Vos=Vs	I <sub>D</sub> =250µA, V <sub>DS</sub> =V <sub>GS</sub>		3.0	3.5	V
Zero Gate Voltage Drain Current	Ipss	V <sub>DS</sub> =500V, V <sub>GS</sub> =0V	T <sub>ch</sub> =25°C	-	-	25	μA
	IDSS	V <sub>DS</sub> =400V, V <sub>GS</sub> =0V	T <sub>ch</sub> =125°C	-	-	250	
Gate-Source Leakage Current	Igss	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V		10	100	nA
Drain-Source On-State Resistance	Ros (on)	I <sub>D</sub> =2.5A, V <sub>GS</sub> =10V	I <sub>D</sub> =2.5A, V <sub>GS</sub> =10V		1.28	1.50	Ω
Forward Transconductance	<b>g</b> fs	I <sub>D</sub> =2.5A, V <sub>DS</sub> =25V	I <sub>D</sub> =2.5A, V <sub>DS</sub> =25V		5	-	S
Input Capacitance	Ciss	V <sub>DS</sub> =25V		-	610	915	pF
Output Capacitance	Coss	V <sub>GS</sub> =0V	V <sub>GS</sub> =0V		66	99	
Reverse Transfer Capacitance	Crss	f=1MHz -		4.7	7.1		
Turn-On Time	td(on)	V <sub>cc</sub> =300V V <sub>cs</sub> =10V I <sub>D</sub> =2.5A		-	10	15	ns
	tr			-	7	10.5	
Turn-Off Time	td(off)			-	45	67.5	
	tf	R <sub>G</sub> =24Ω	$R_G=24\Omega$ - 13.		13.5	20.3	
Total Gate Charge	QG	Vcc=250V	V <sub>cc</sub> =250V I <sub>D</sub> =5A		21	32	nC
Gate-Source Charge	QGS	In=5A			6	9	
Gate-Drain Charge	Q <sub>GD</sub>	V <sub>GS</sub> =10V		-	5.5	8.3	
Avalanche Capability	lav	L=5.01mH, Tch=25°C	L=5.01mH, Tch=25°C		-	-	А
Diode Forward On-Voltage	V <sub>SD</sub>	I <sub>F</sub> =5A, V <sub>GS</sub> =0V, T <sub>ch</sub> =25°C	I <sub>F</sub> =5A, V <sub>GS</sub> =0V, T <sub>ch</sub> =25°C		0.86	1.30	V
Reverse Recovery Time	trr	I <sub>F</sub> =5A, V <sub>GS</sub> =0V	I <sub>F</sub> =5A, V <sub>GS</sub> =0V		0.28	-	μs
Reverse Recovery Charge	Qrr	-di/dt=100A/µs, Tch=25°C		-	1.8	-	μC

#### Thermal Characteristics

Description	Symbol	Test Conditions	min.	typ.	max.	Unit
Thermal resistance	Rth (ch-c)	Channel to Case			1.200	°C/W
	Rth (ch-a)	Channel to Ambient			62.0	°C/W

Note \*1 : Tch≤150°C

Note \*2 : Stating Tch=25°C, I<sub>As</sub>=2A, L=78.3mH, Vcc=50V, R<sub>G</sub>=50Ω

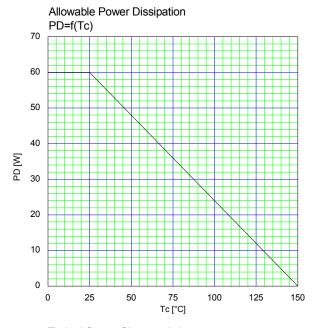
E<sub>As</sub> limited by maximum channel temperature and avalanche current.

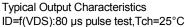
See to 'Avalanche Energy' graph.

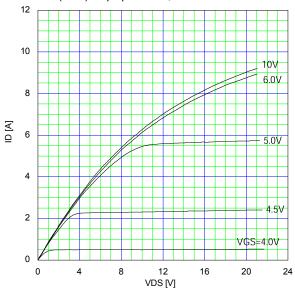
Note \*3: Repetitive rating: Pulse width limited by maximum channel temperature.

See to the 'Transient Themal impeadance' graph.

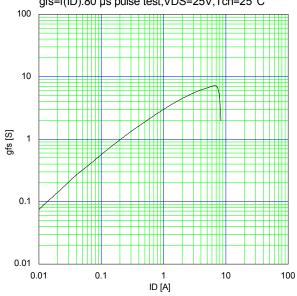
Note \*4 : IF $\leq$ -ID, -di/dt=100A/ $\mu$ s, Vcc $\leq$ BVDss, Tch $\leq$ 150°C. Note \*5 : IF $\leq$ -ID, dv/dt=5.3kV/ $\mu$ s, Vcc $\leq$ BVDss, Tch $\leq$ 150°C.



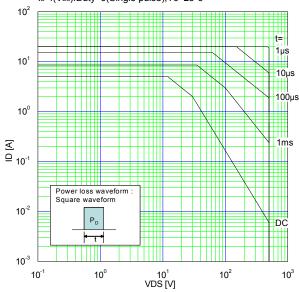




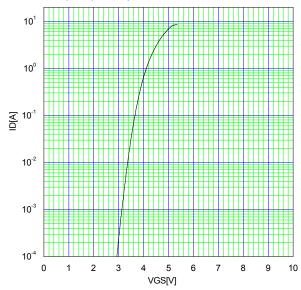
Typical Transconductance gfs=f(ID):80 µs pulse test,VDS=25V,Tch=25°C



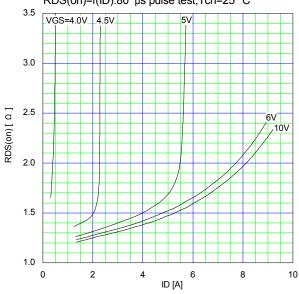
Safe Operating Area
ID=f(VDS):Duty=0(Single pulse),Tc=25°c



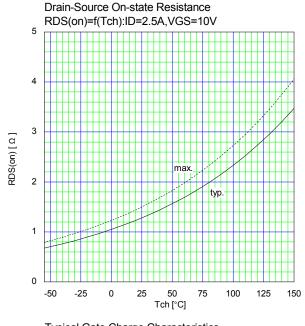
Typical Transfer Characteristic ID=f(VGS):80 µs pulse test,VDS=25V,Tch=25 °C

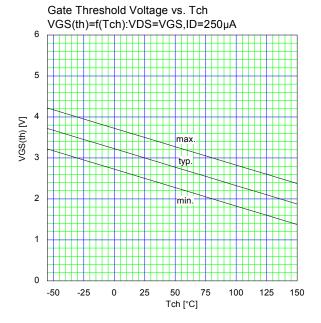


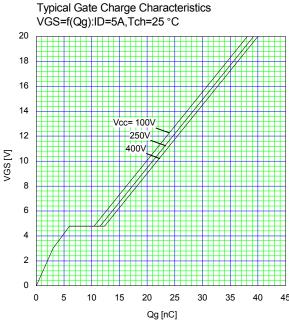
Typical Drain-Source on-state Resistance RDS(on)=f(ID):80 µs pulse test,Tch=25 °C

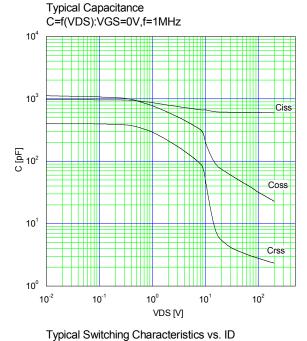


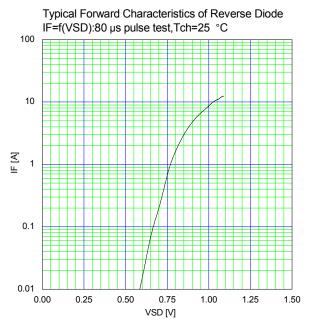
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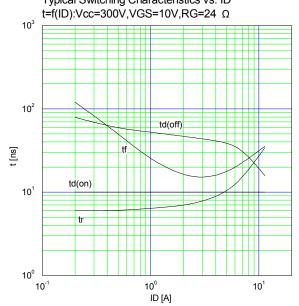


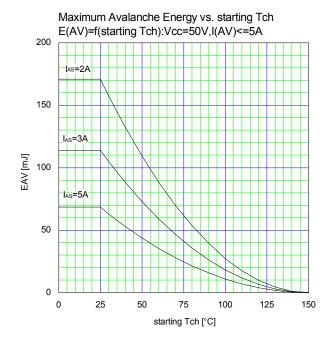


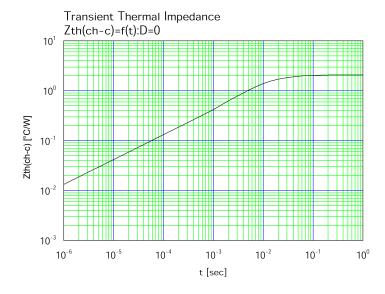












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